

**TITLE: METHOD OF IMPROVING COPPER INTERCONNECTS OF
SEMICONDUCTOR DEVICES FOR BONDING**
Inventor: Salman Akram
Docket No.: 3854.3US

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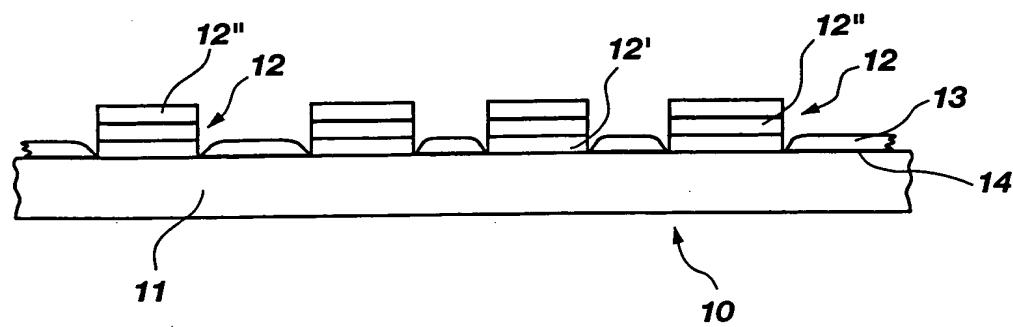


Fig. 1

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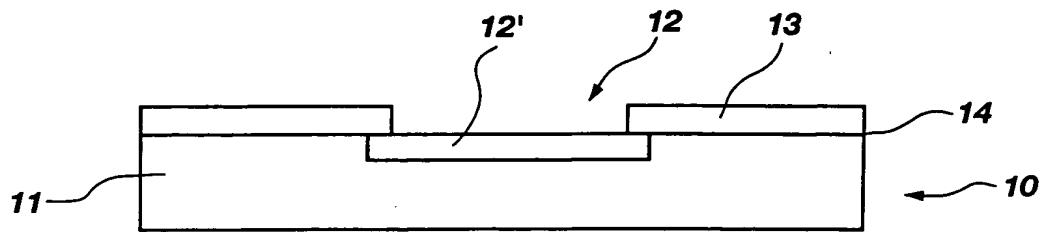


Fig. 2A

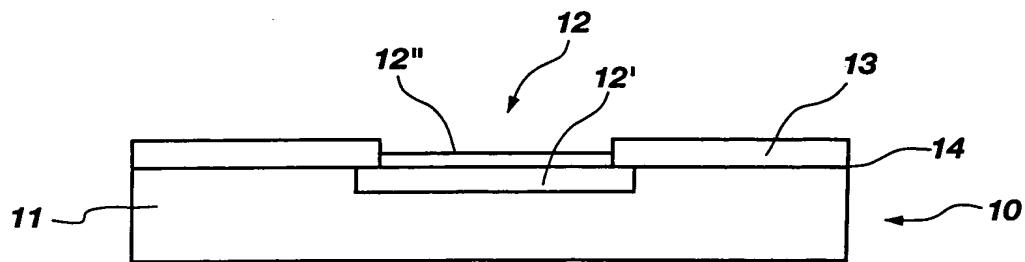


Fig. 2B

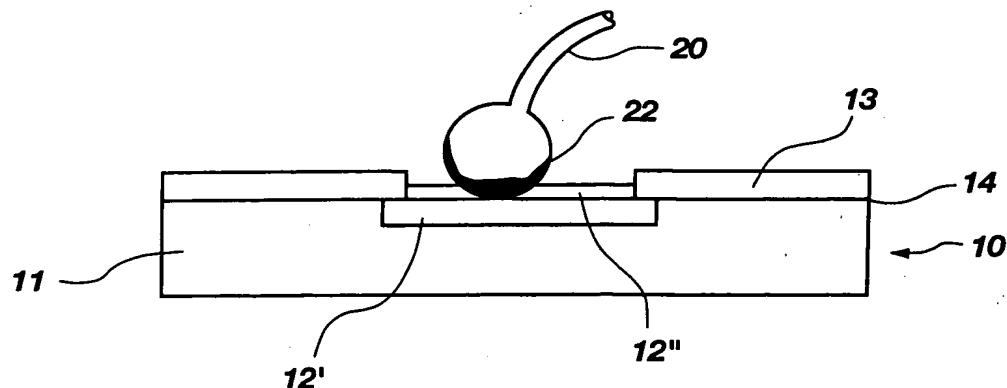


Fig. 2C

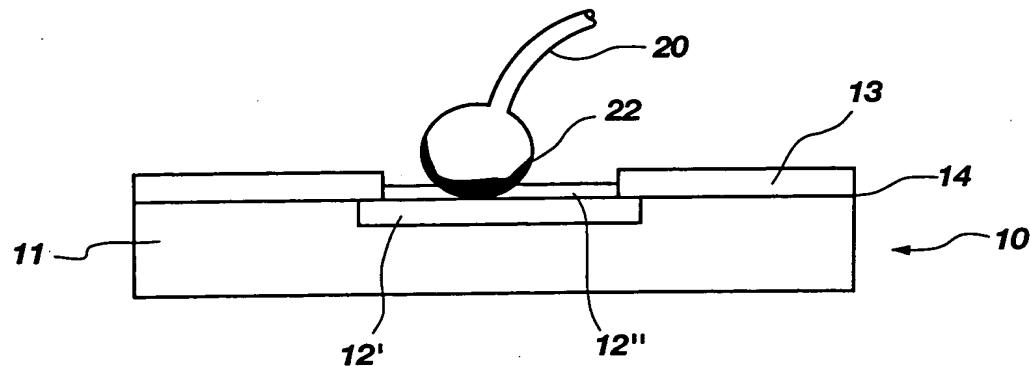


Fig. 2D

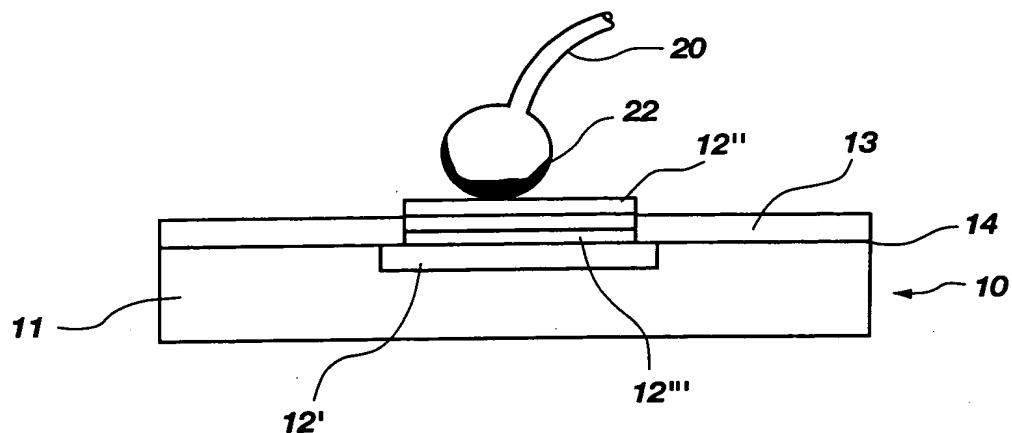


Fig. 2E

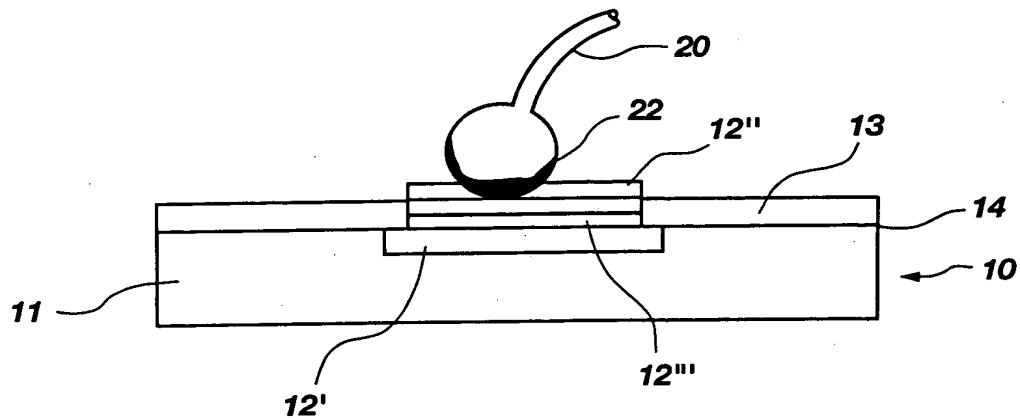


Fig. 2F

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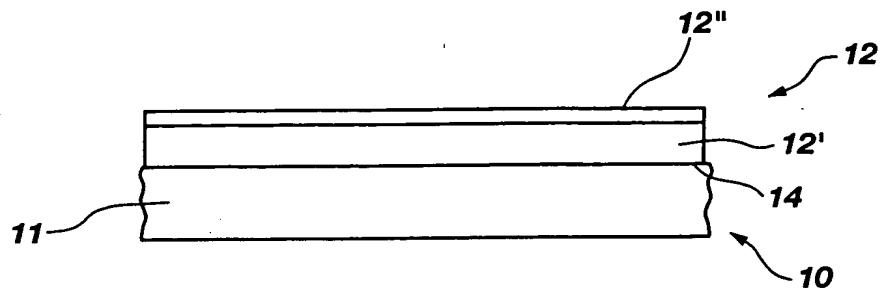


Fig. 3A

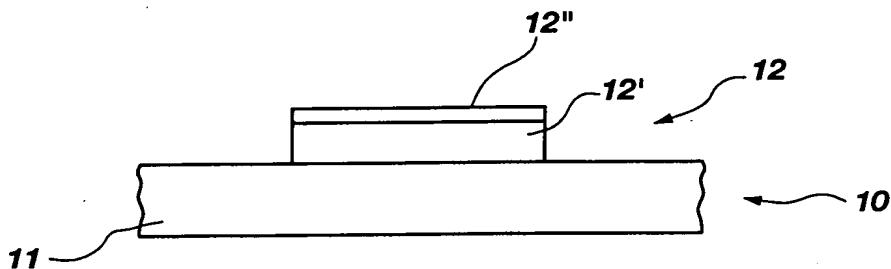


Fig. 3B

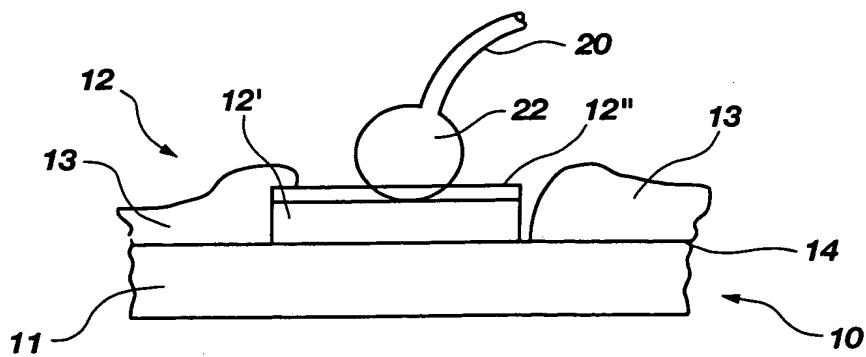


Fig. 3C

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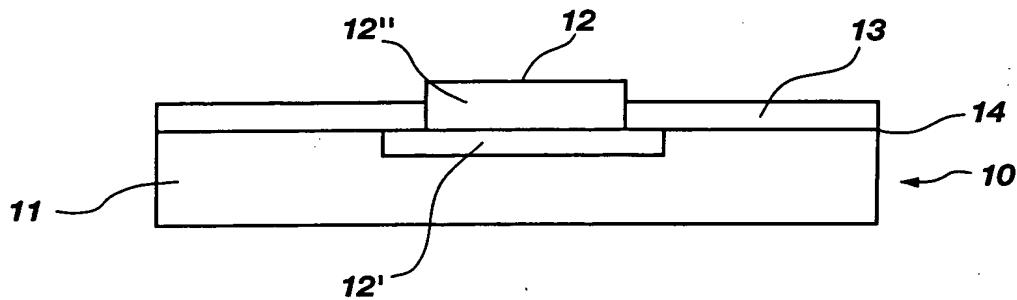


Fig. 4A

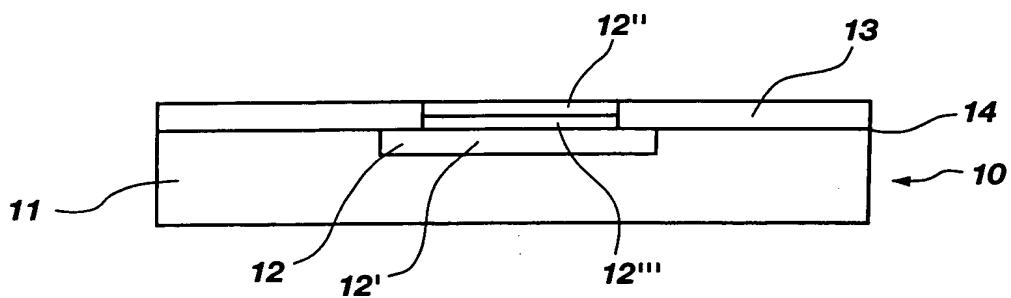


Fig. 4B

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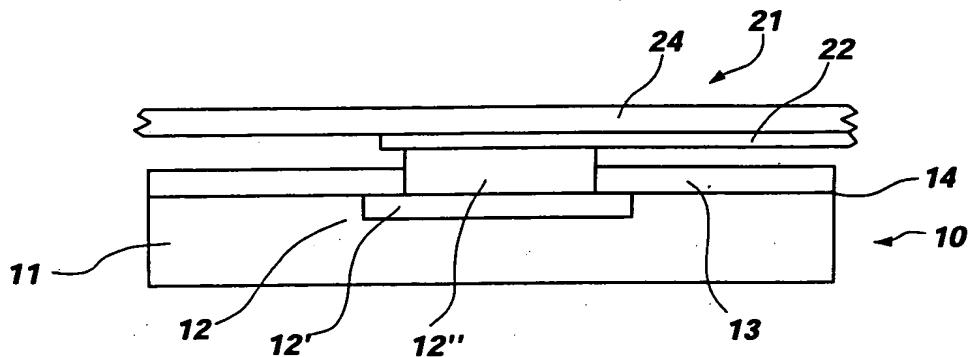


Fig. 4C

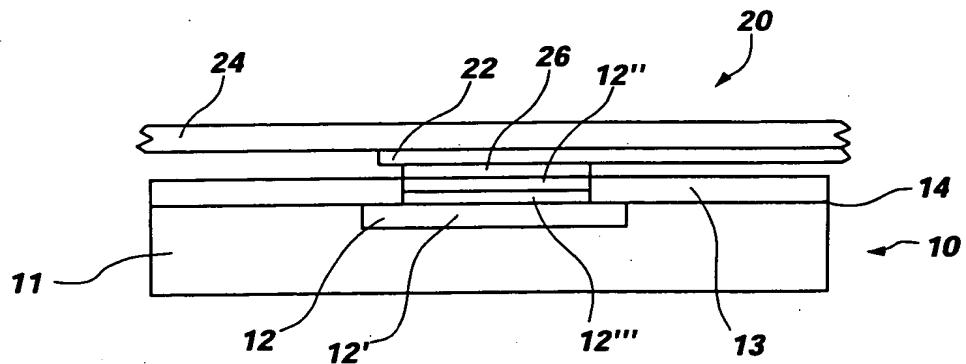


Fig. 4D

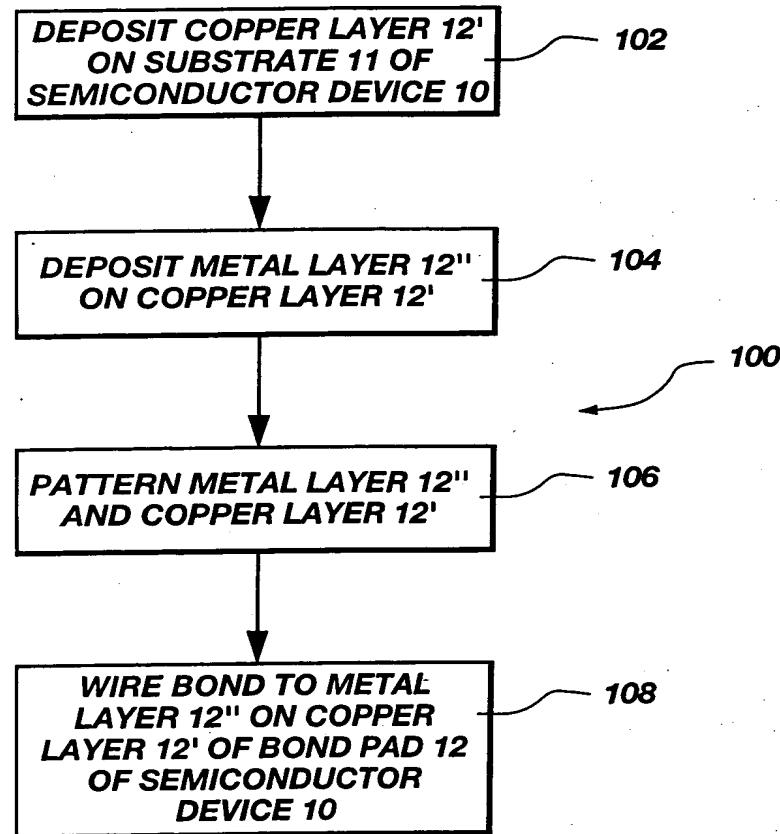


Fig. 5A

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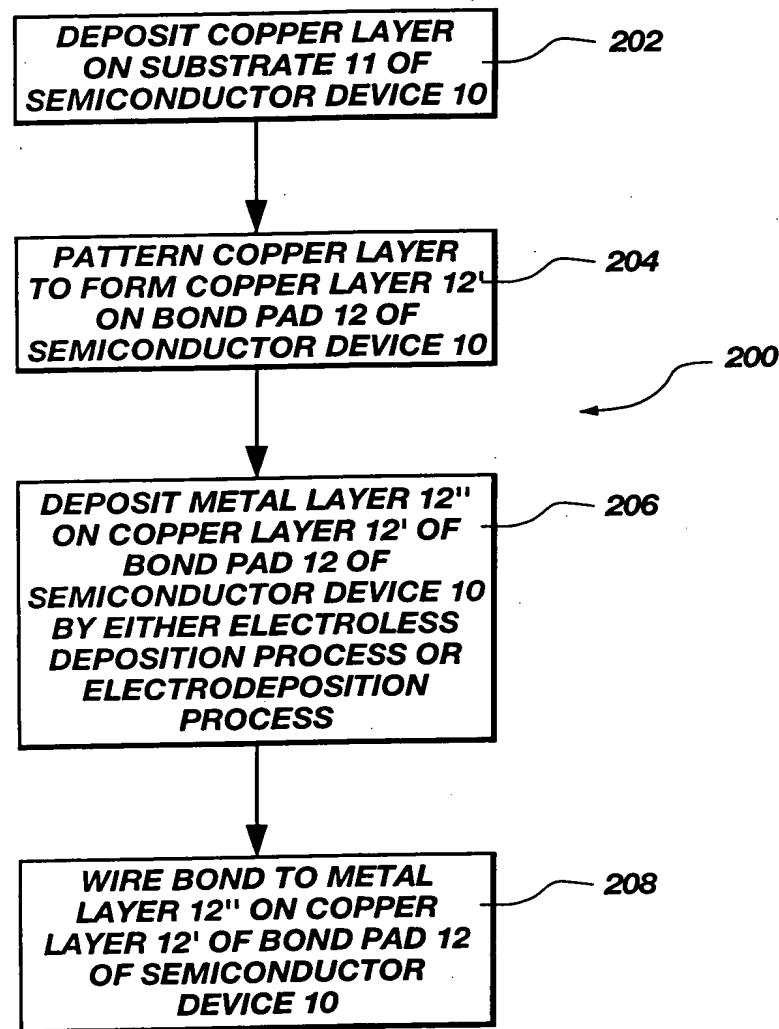


Fig. 5B

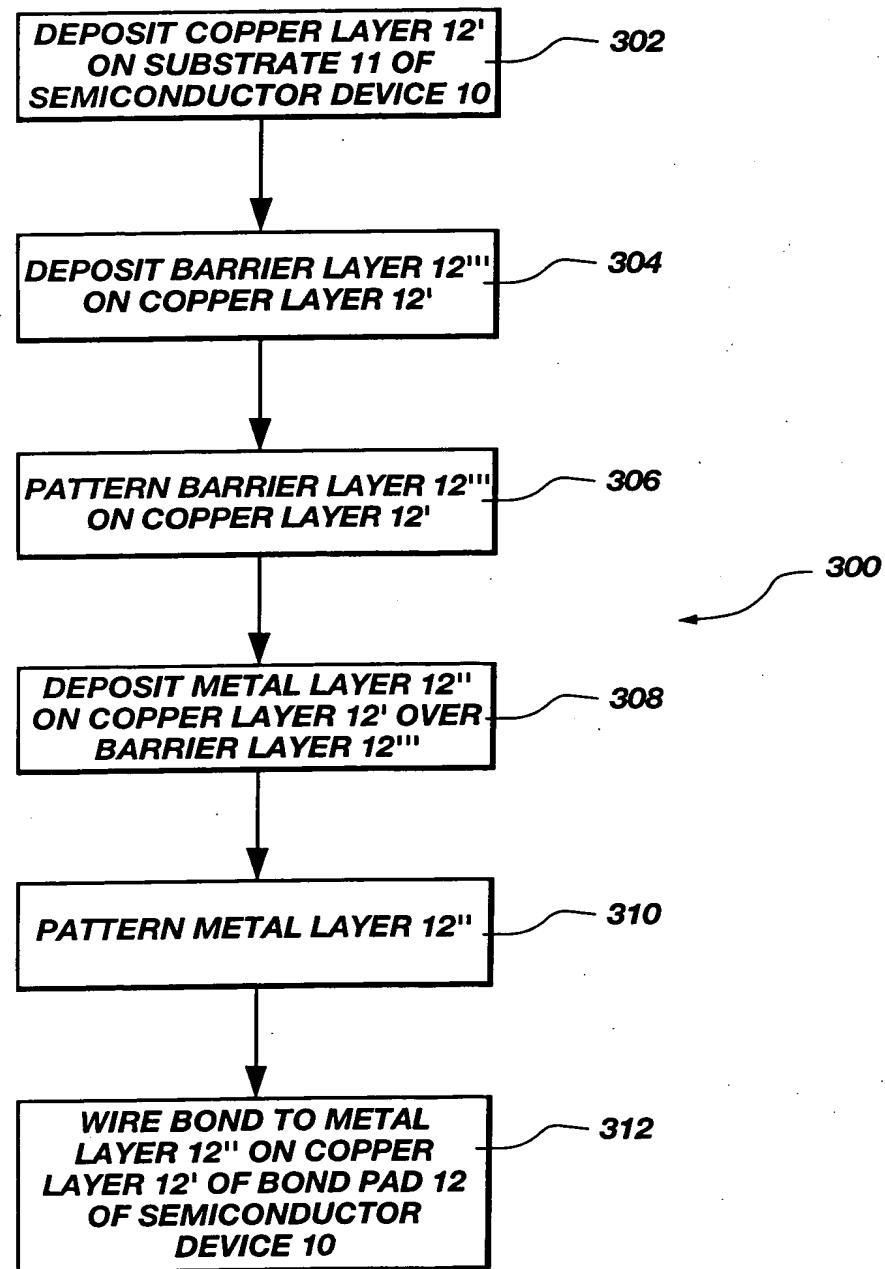


Fig. 5C

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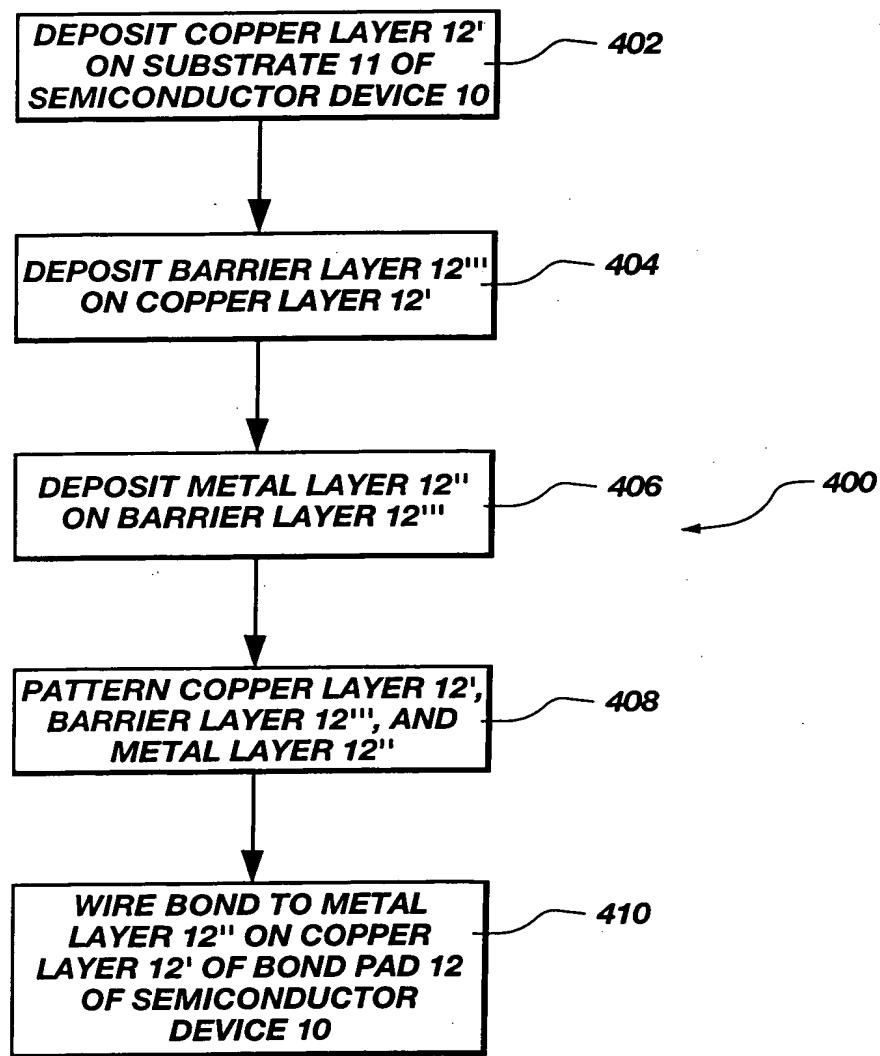


Fig. 5D

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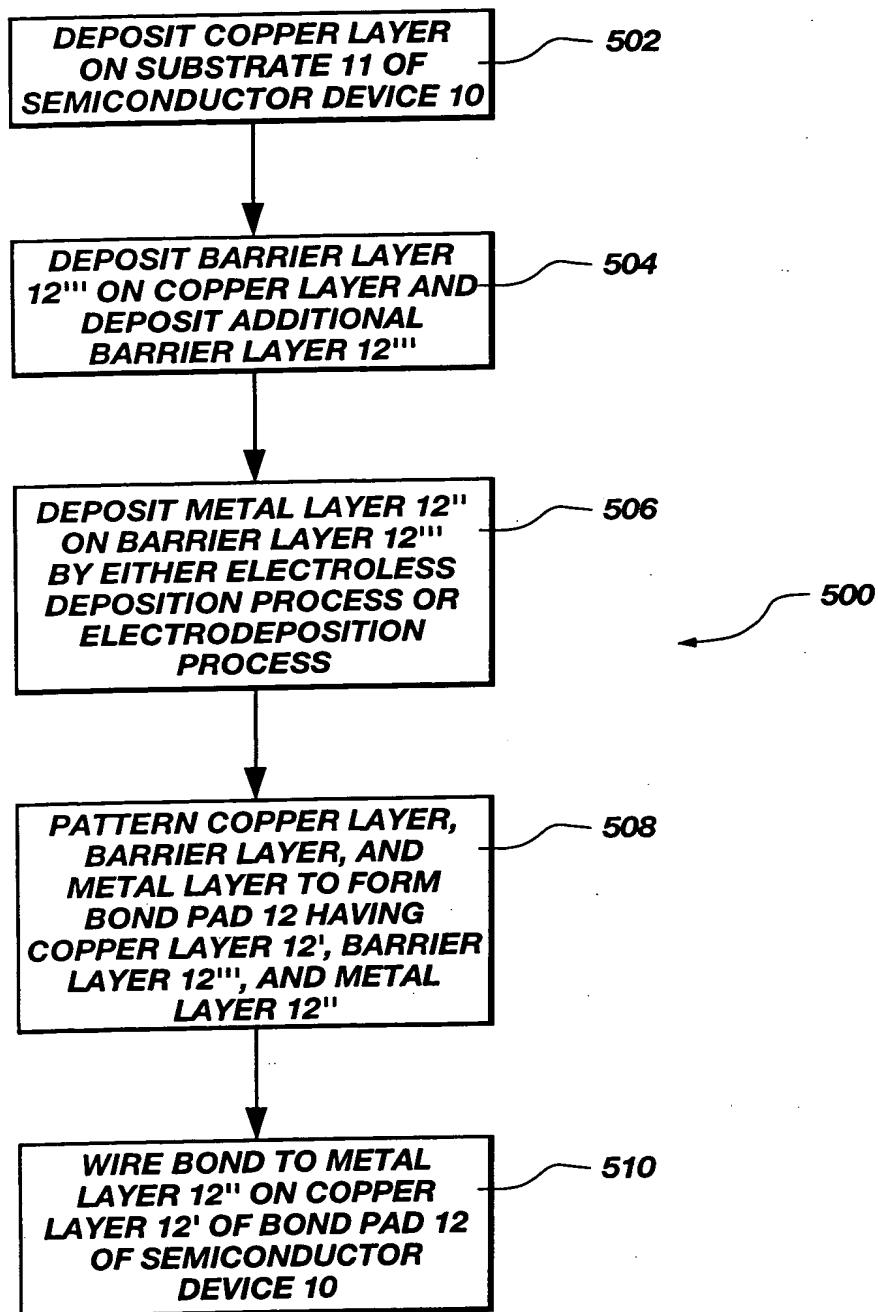


Fig. 5E

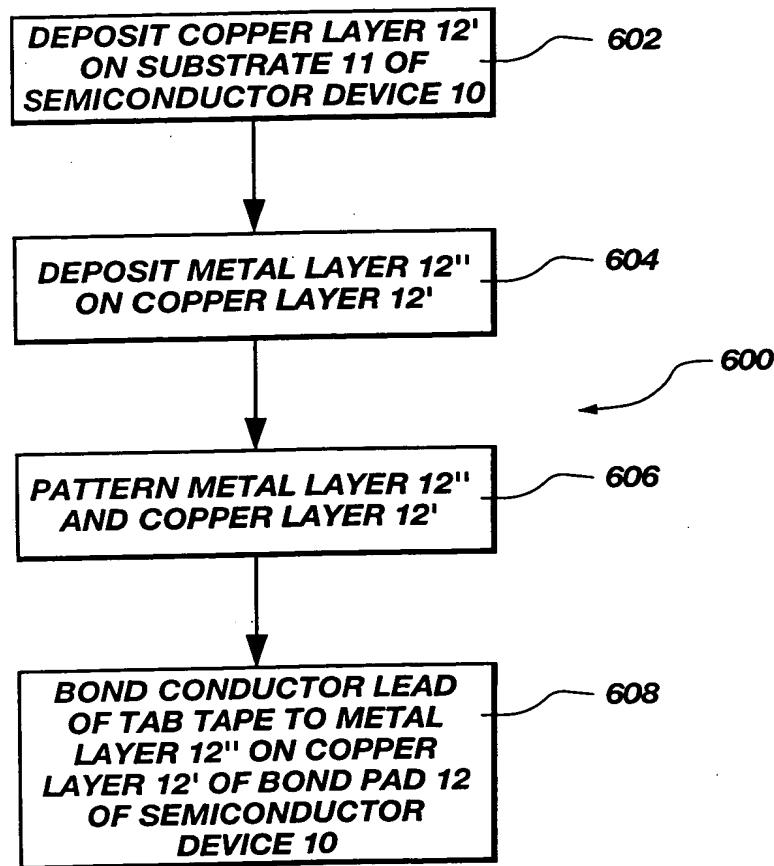


Fig. 5F

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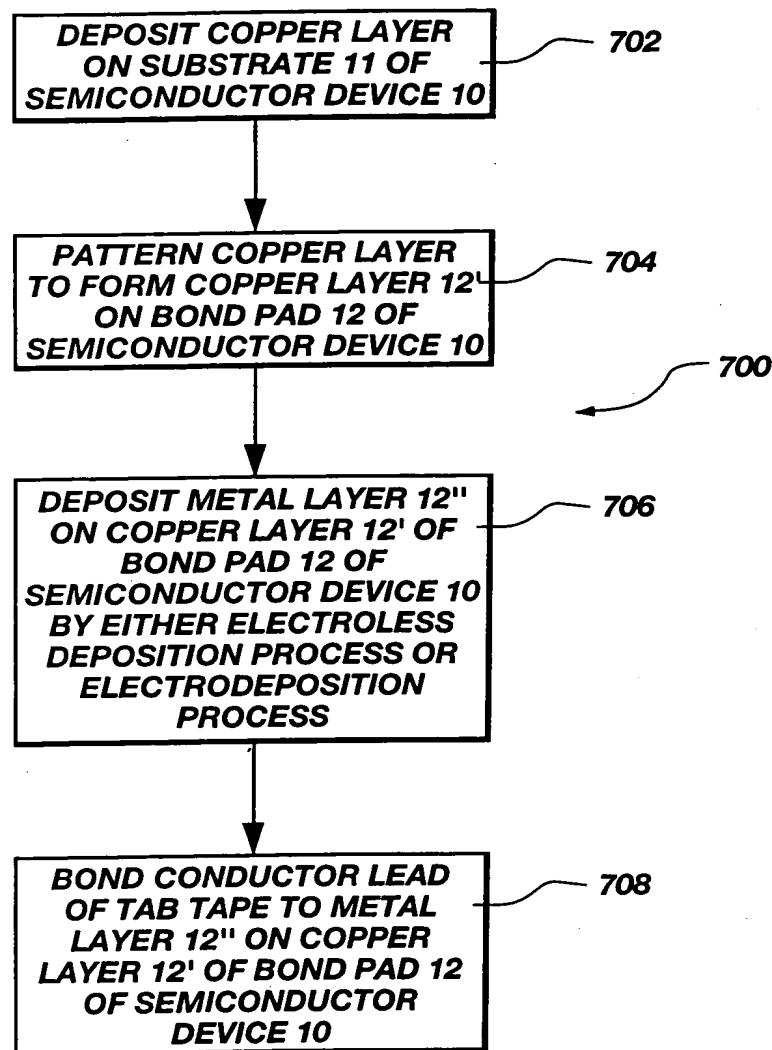


Fig. 5G

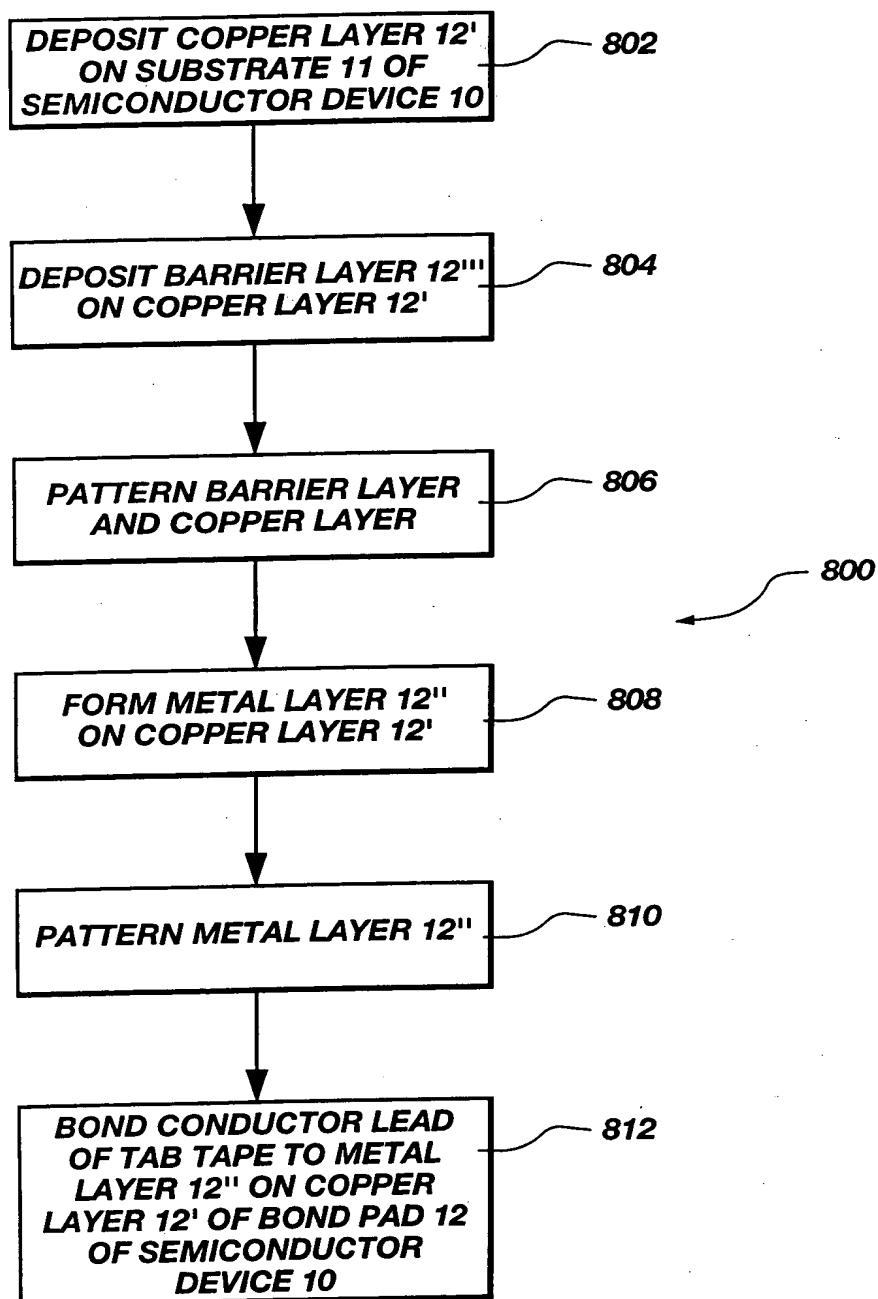


Fig. 5H

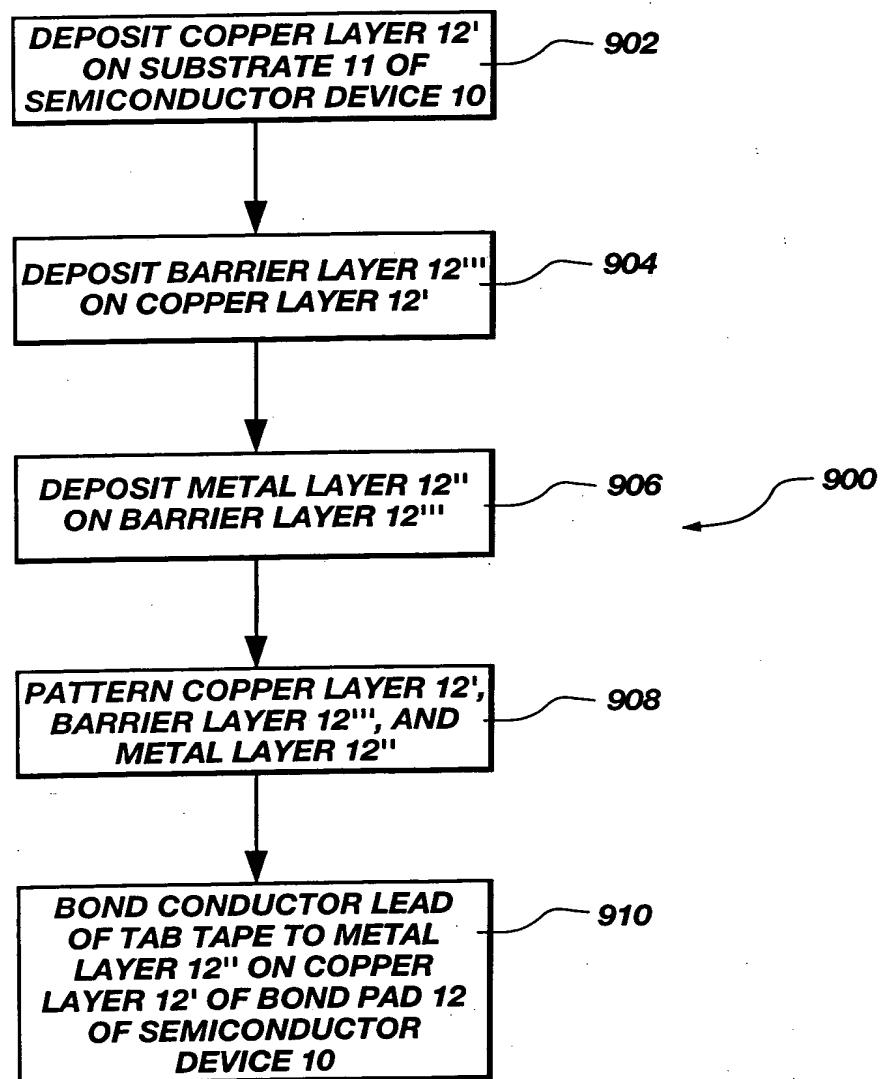


Fig. 5I

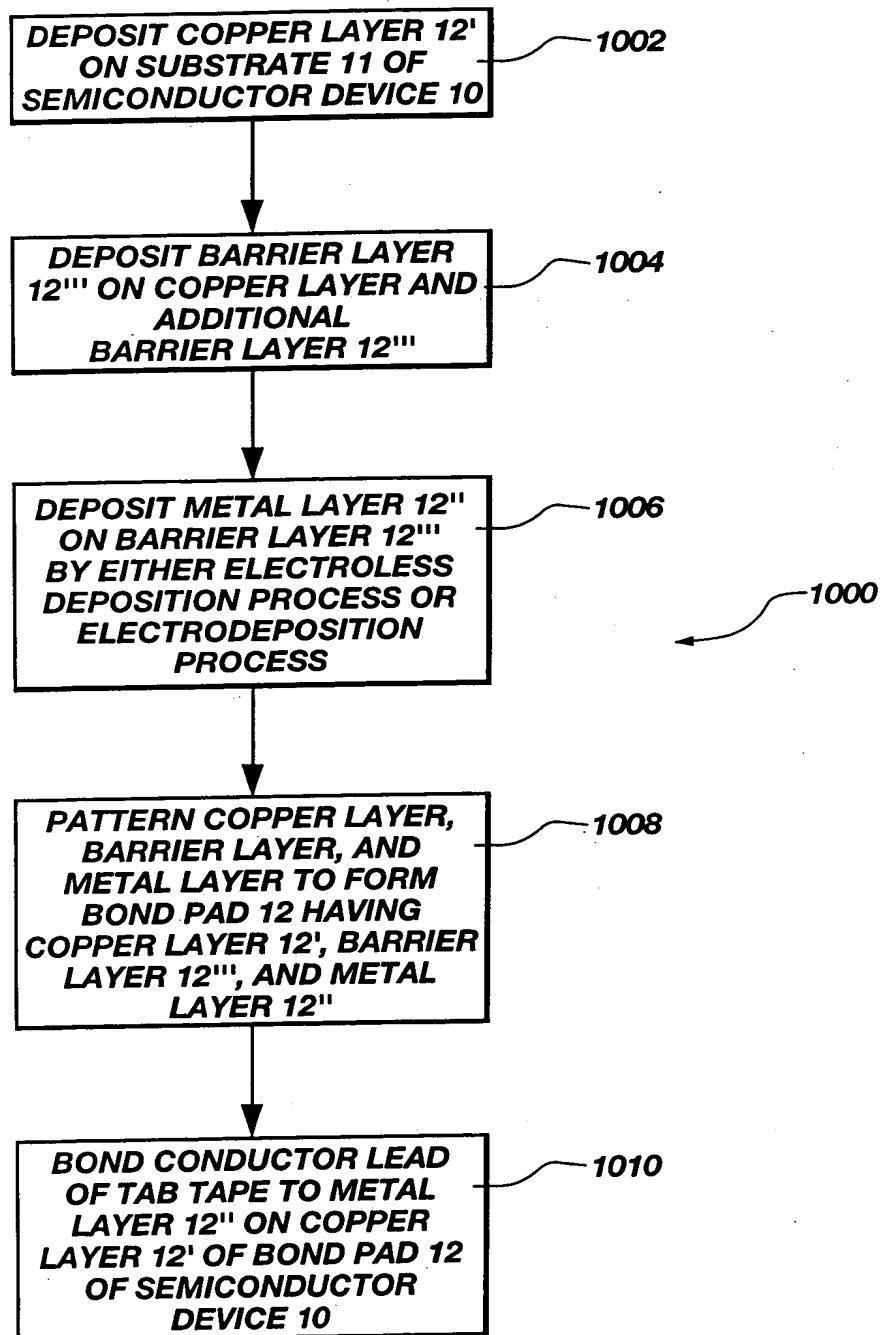


Fig. 5J